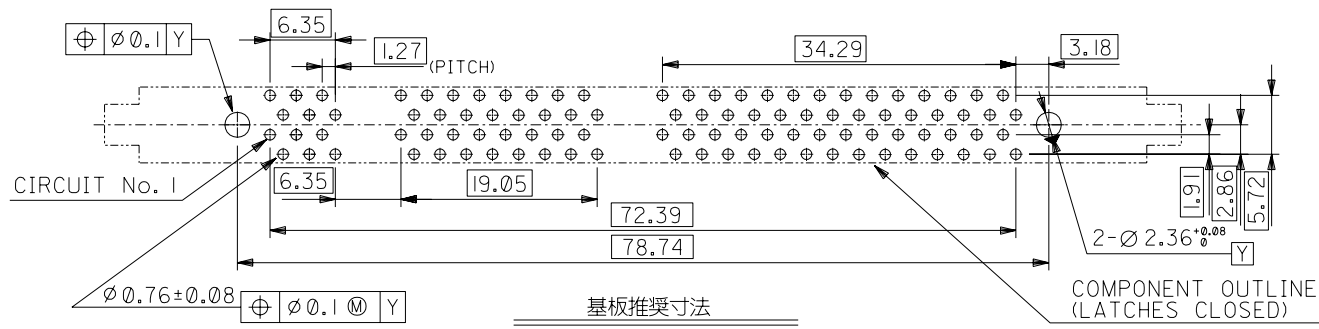
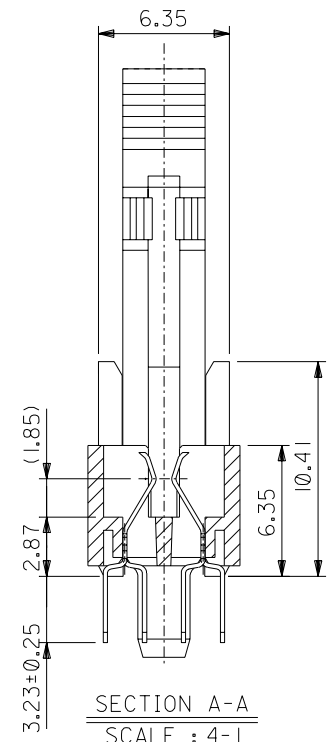
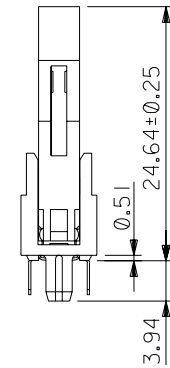
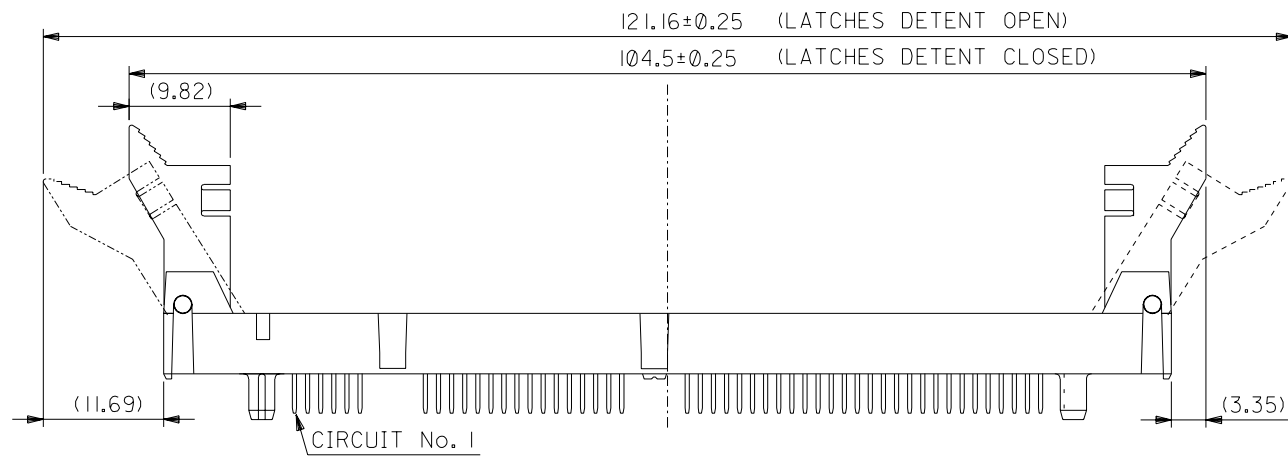
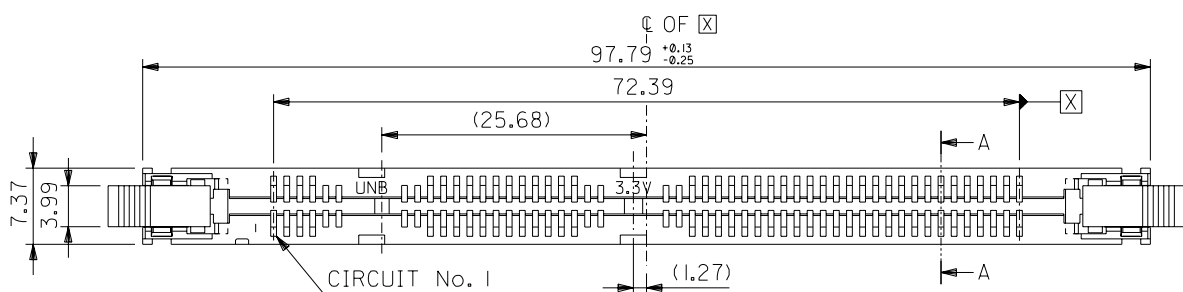


DWG. NO. SD-71251-5101  
 DIMENSIONS IN METRIC DO NOT SCALE DRAWING



基板推奨寸法  
RECOMMENDED P.C.B. LAYOUT

COMPONENT OUTLINE  
(LATCHES CLOSED)

角度 ANGLE	±3°				
30°以上 OVER	±0.3				
10°以上 OVER 30°未滿 UNDER	±0.25	A	変更 REVISD (J2004-4509)	Y.W.	04/05/31
10°未滿 UNDER	±0.2	0	新規作成 PROPOSED (JD90709)	M.S.	98/11/12
一般公差 GENERAL TOLERANCES		記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE

材料 MATERIAL	注参照 SEE NOTES
仕上げ FINISH	注参照 SEE NOTES
適用電線範囲 INS. RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '98/11/12	CHK'D BY '98/11/12
J. Kinata	H. Saito
APP'D BY '98/11/12	尺度 SCALE 2 - 1
日付 DATE	

MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
REVISE ONLY ON CAD SYSTEM	
TITLE 名称 1.27 PITCH DIMM 100 CIRCUIT MULTI-KEY HOUSING ASS'Y -LEAD FREE-	
DWG. NO.	SHEET 1 OF 2 REV
SD-71251-5101	A

DWG. NO. SD-71251-5101

E

D

C

B

A

MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

- NOTE: 1. モジュールの推奨基板厚: 1.27±0.1 (パッド含む)  
 CARD SLOT ACCEPTS 1.27±0.1 MODULE THICKNESS. (MEASURED OVER P.C. PADS).  
 2. ペグには、基板に対する挿入力が発生します。  
 ALL PEGS ARE INTERFERENCE FITS TO PCB UNLESS NOTED ON THE DWG.  
 3. 製品仕様については、PS-71251-5101をご参照下さい。  
 REFER TO PRODUCT SPEC. PS-71251-5101 FOR PERFORMANCE SPECIFICATIONS.  
 4. 梱包形態は、トレイ梱包です。  
 PRODUCT IS PACKAGED IN TRAYS.  
 5. 推奨モジュール・レイアウトはMO-161をご参照下さい。  
 RECOMMENDED MODULE LAYOUT SHALL BE PER MO-161.  
 6. モジュール基板パッドの推奨メッキ仕様  
 金: 0.76MICROMETER MIN.  
 ニッケル下地: 2.0MICROMETER MIN.  
 RECOMMENDED PLATING ON MODULE PADS:  
 0.76MICROMETER MIN. HARD GOLD OVER 2.0MICROMETER MIN. NICKEL.

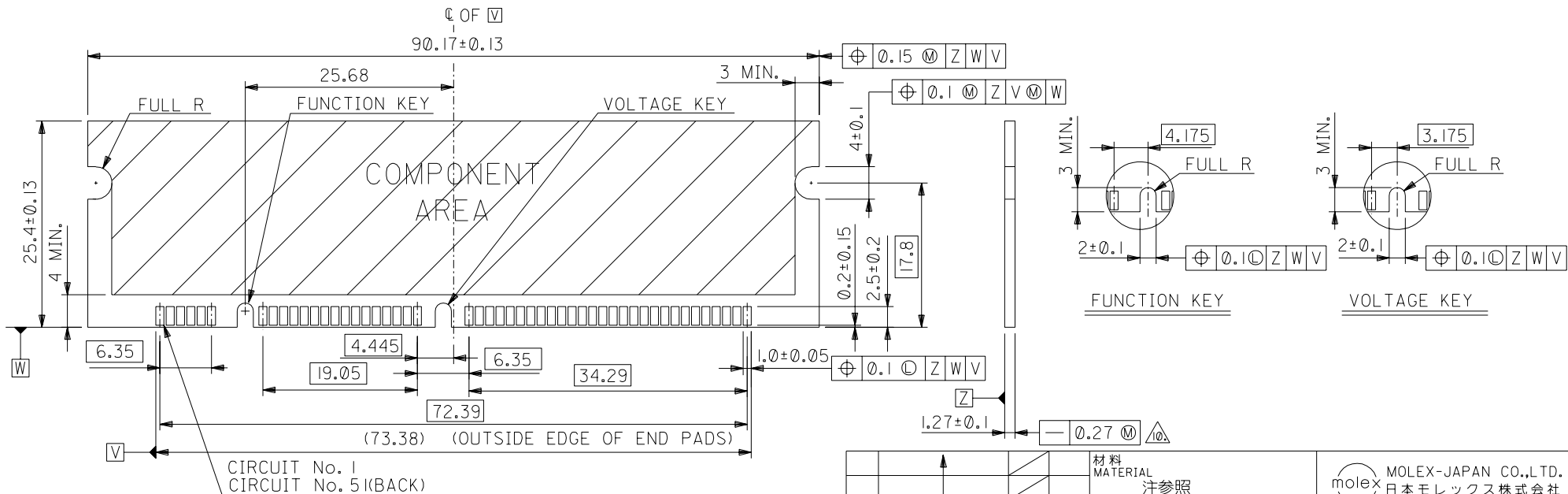
7. 製造日コードはハウジングの側面に刻印されます。  
 PRODUCT WILL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.  
 8. 材質  
 ハウジング: 耐熱性樹脂 (黒色)  
 ラッチ: 耐熱性樹脂 (アイボリー)  
 ターミナル: リン青銅  
 MATERIALS:  
 HOUSING- HIGH-TEMP THERMOPLASTIC COLOR: BLACK  
 LATCHES - HIGH-TEMP THERMOPLASTIC COLOR: IVORY  
 TERMINAL- PHOSPHOR BRONZE  
 9. メッキ仕様  
 接点部: 金メッキ0.05-0.25MICROMETER  
 パラジウムニッケル下地0.76MICROMETER MIN.  
 半田付け部: 錫メッキ 3.8IMICROMETER MIN.  
 下地メッキ: ニッケルメッキ1.27MICROMETER MIN.  
 PLATING:  
 CONTACT AREA: GOLD 0.05-0.25MICROMETER OVER PALLADIUM-NICKEL

SOLDER TAILS: TIN  
 3.8IMICROMETER MIN.  
 UNDERPLATE: NICKEL 1.27MICROMETER MIN.

△モジュール基板の真直度は、底辺より4mmの範囲に適用。  
 STRAIGHTNESS OF MODULE APPLIES TO THE AREA FROM THE BOTTOM OF THE CARD UP 4.

11. 電解メッキなどのために、パッドにタブを設ける場合は、それがコネクタのコンタクト部を損傷する原因とならないよう、ご配慮下さい。

IF TIE BARS ARE ATTACHED TO PADS, THE TIE BAR SHOULD BE ON AN INTERNAL LAYER, SO THAT THE REMNANT CANNOT CAUSE DAMAGE TO THE CONTACTS.



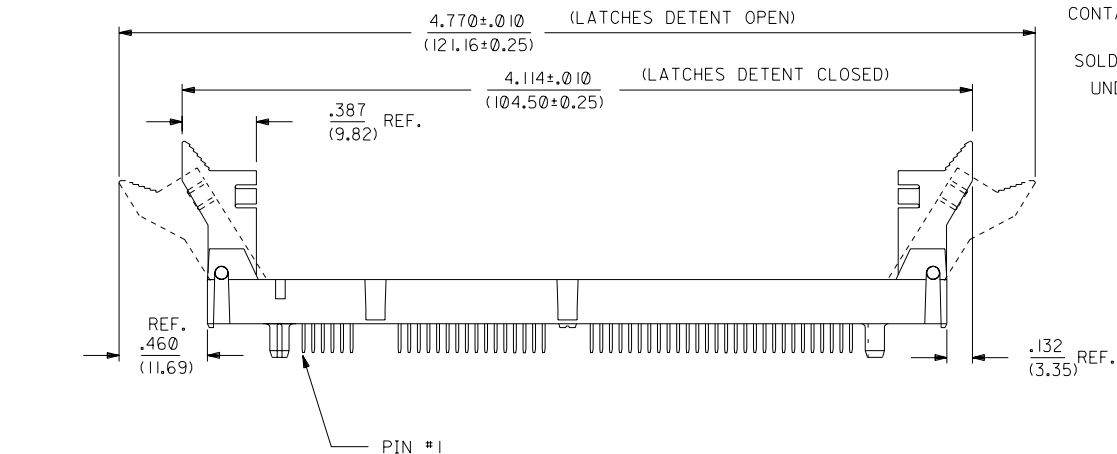
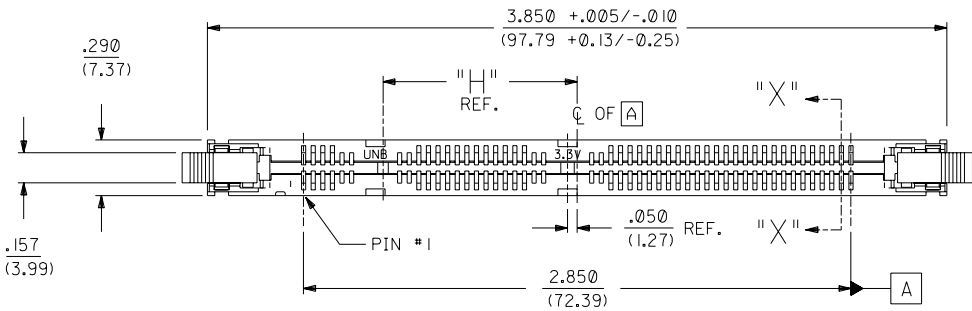
基板推奨寸法  
 RECOMMENDED P.C.B. LAYOUT

角度 ANGLE	±3°
30 以上 OVER	+0.3
10 以上 OVER 30 未満 UNDER	+0.25
10 未満 UNDER	+0.2

一般公差 GENERAL TOLERANCES	記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE
0		SHEET 1 OF 2 参照 SEE SHEET 1 OF 2		
				APP'D BY J. Kinata
				CHK'D BY H. Saito
				尺度 SCALE 2 - 1

材料 MATERIAL	注参照 SEE NOTES
仕上げ注参照 FINISH SEE NOTES	
適用電線範囲 WIRE RANGE	—
被覆外径 INS. RANGE	—
DRAWN BY '98/11/12 J. Kinata	CHK'D BY H. Saito

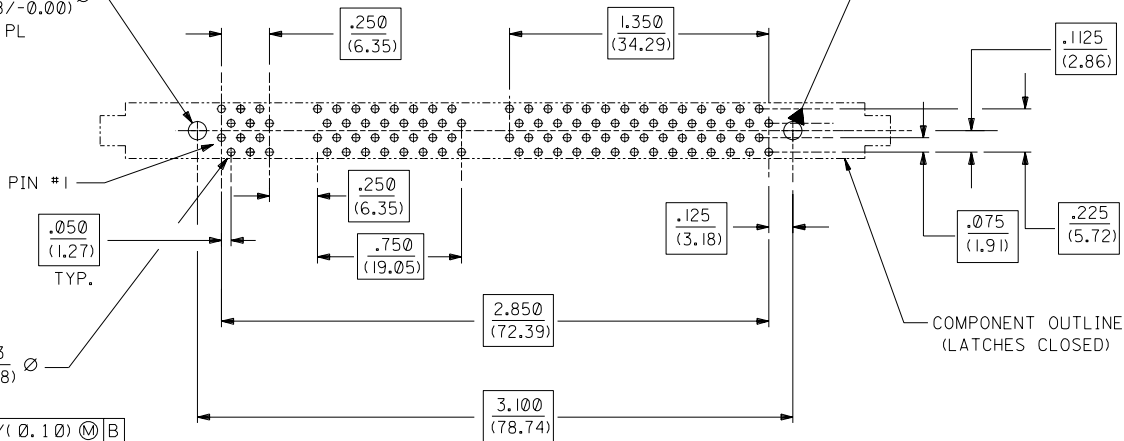
材料 MATERIAL	MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
仕上がり注参照 FINISH SEE NOTES	REVISE ONLY ON CAD SYSTEM
適用電線範囲 WIRE RANGE	TITLE 名称 1.27 PITCH DIMM 100 CIRCUIT MULTI-KEY HOUSING ASS'Y -LEAD FREE-
被覆外径 INS. RANGE	DWG. NO. SHEET 2 OF 2 REV
DRAWN BY '98/11/12 J. Kinata	SD-71251-5101 A



71251-5101 SHOWN

⊕ ∅ .004 / (0.10) B 2 PL

.093 +.003 / -.000  
(2.36 +0.08 / -0.00) ∅  
2 PL



RECOMMENDED  
P.C. BOARD HOLE PATTERN  
(CONNECTOR SIDE)

NOTES:

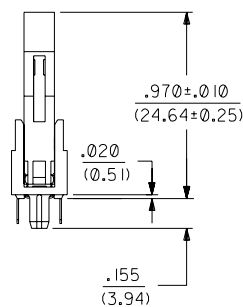
- CARD SLOT ACCEPTS .050 ± .004 (1.27 ± 0.10) MODULE THICKNESS. (MEASURED OVER P.C. PADS).
- ALL PEGS ARE INTERFERENCE FITS TO PCB UNLESS NOTED ON THE DWG.
- REFER TO PRODUCT SPEC. PS-71243 FOR PERFORMANCE SPECIFICATIONS.
- PRODUCT IS PACKAGED IN TRAYS.
- RECOMMENDED MODULE LAYOUT SHALL BE PER MO-161.
- RECOMMENDED PLATING ON MODULE PADS: 30 MICROINCH/(0.76 MICROMETER) MINIMUM HARD GOLD (AU) OVER 79 MICROINCH/(2.0 MICROMETER) MINIMUM NICKEL (NI).
- PRODUCT WILL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.

MATERIALS:

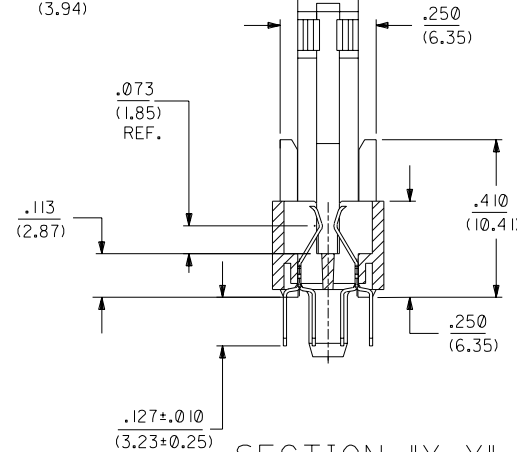
HOUSING - GLASS FILLED LIQUID CRYSTAL POLYMER (LCP), UL 94V-0, COLOR: BLACK.  
TERMINAL - PHOSPHOR BRONZE  
LATCHES - GLASS FILLED HIGH TEMPERATURE NYLON, UL 94V-0, COLOR: IVORY.

PLATING:

CONTACT AREA: MOLEX EBI LUBRICANT OVER  
GOLD (AU): THICKNESS=10 MICROINCH/(0.25 MICROMETER) MINIMUM.  
SOLDER TAILS: TIN (Sn): THICKNESS=150 MICROINCH/(3.81 MICROMETER) MINIMUM.  
UNDERPLATE: NICKEL (NI) OVER ENTIRE CONTACT.



NOTE FOR LEAD FREE CONVERSION:  
THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.



SECTION "X-X"

SCALE 4:1

2	A1			
1	C1	1		
MFG, SH.	REV.	LTR.	REVISIONS	

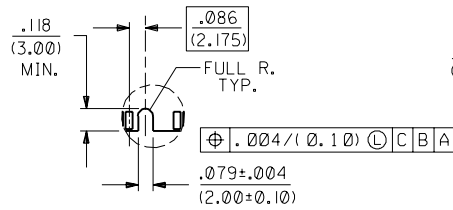
DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°		TITLE 0.050 PITCH DIMM 100 CKT MULTI-KEY SALES DRAWING	
3 PLATE ± .005	INCH	---	METRIC
2 PLATE ± --- ± 0.13	---	---	---
1 PLATE --- ± 0.25	---	---	---
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MOLEX INCORPORATED LITSE, ILL. 60532	SHEET NO. 1 OF 2 DATE 03/26/96
DRWG. BY JCL	CHK'D. BY DCB	FILE NAME ST125151.DGN	DRWG. NO. SDA-71251-5***
APPRD. BY DCB	SCALE 2:1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	

C1	ADD LEAD FREE NOTE ECN# UCP2004-1732 DMORGAN 04/03/09
C	CHANGE PLATING ECN# UDT2002-0772 DMORGAN 02/01/22
B	CHG Sn-Pb THICKNESS ECN# UDT1999-0454 DMORGAN 99/08/09
A1	REVISED PER ECR# U80435 97-8-8 LAURX
A	REVISED PER ECR# U70042 96-7-23 LAURX
2	REVISED PER ECR# U61175 4-10-96 JCL
	X-RELEASE PER ECR# U61175 3-26-96 JCL

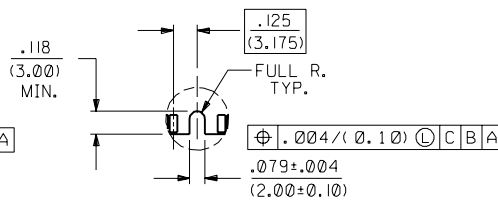
PART NUMBER	DESCRIPTION	FUNCTION KEY	VOLTAGE KEY	DIM. "H"
71251-5101	3.3 VOLT UNBUFFERED	OFFSET RIGHT	CENTER	.1011 (25.68)
71251-5102	5.0 VOLT UNBUFFERED	OFFSET RIGHT	OFFSET LEFT	.1011 (25.68)

**NOTES:**

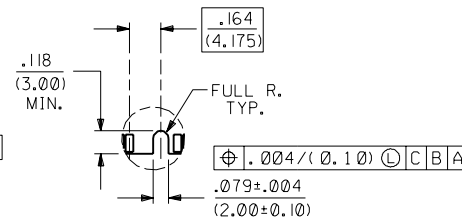
1. STRAIGHTNESS OF MODULE APPLIES TO THE AREA FROM THE BOTTOM OF THE CARD UP .157/(4.00).
2. IF TIE BARS ARE ATTACHED TO PADS, THE TIE BAR SHOULD BE ON AN INTERNAL LAYER, SO THAT THE REMNANT CANNOT CAUSE DAMAGE TO THE CONTACTS.



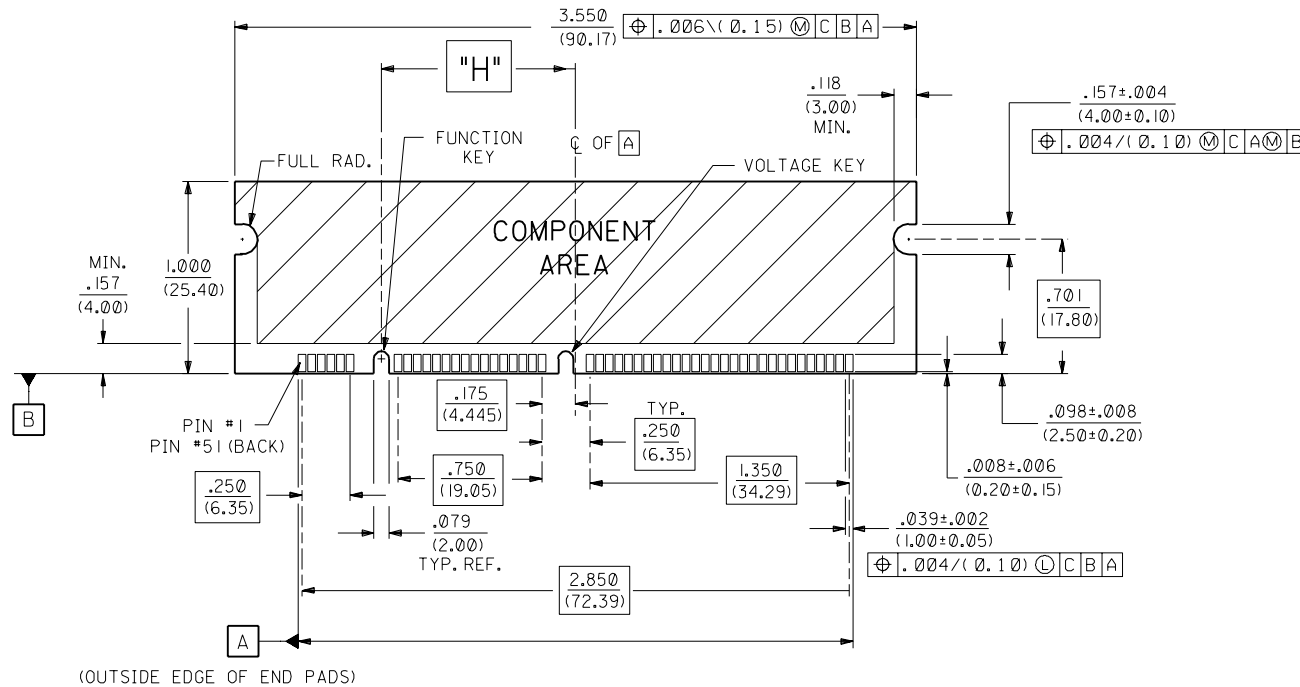
OFFSET LEFT KEY



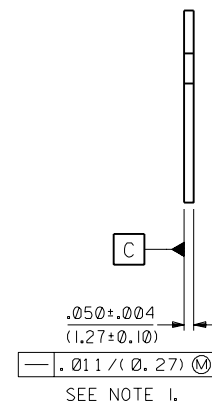
CENTERED KEY



OFFSET RIGHT KEY



RECOMMENDED MODULE LAYOUT  
100 CKT 3.3V UNBUFFERED



REV.	DESCRIPTION
A1	SEE SHEET 1
A	SEE SHEET 1
2	SEE SHEET 1
1	SEE SHEET 1

DIMENSIONS SHOWN (METRIC) INCH		TITLE	
UNLESS OTHERWISE SPECIFIED TOLERANCES ANGULAR ± 1/2°		.050 PITCH DIMM	
5 PLACE ± .005 ---		100 CKT MULTI-KEY	
2 PLACE ± .01 ± 0.13		SALES DRAWING	
1 PLACE --- ± 0.25		MOLEX INCORPORATED SHEET NO. 2 DATE 03/26/96	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MFG. SH. REV. LTR. REVISIONS	
DRWG. NO. SDA-71251-5***		PART NO. SEE CHART	
DRW'G. BY DCB		FILE NAME 5725152.DWG	
APP'D. BY DCB SCALE 2: 1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	